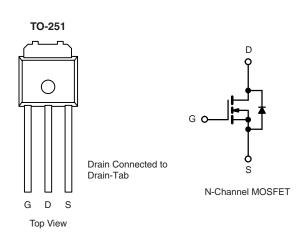


N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
100	0.019 at V_{GS} = 10 V	50		



FEATURES

- Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % Rg Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	- v	
	T _C = 25 °C	1-	50		
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 125 °C	I _D	43		
Pulsed Drain Current	I _{DM}	150	А		
Continuous Source Current (Diode Conduction)	۱ _S	43			
Avalanche Current	I _{AS}	3			
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ	
Maria Barra Disata di sa	T _C = 25 °C	P _D	96 ^b	w	
Maximum Power Dissipation	T _A = 25 °C		3 ^a	7	
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
	$t \le 10 s$	R _{thJA}	15	18	°C/W		
Junction-to-Ambient ^a	Steady State		40	50			
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1			

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50		
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250	1	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.019			
	R _{DS(on)}	V_{GS} = 10 V, I _D = 3 A, T _J = 125 °C		0.020		0	
Drain-Source On-State Resistance ^b		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}, \text{ T}_{J} = 175 \text{ °C}$		0.025		Ω	
		V _{GS} = 6 V, I _D = 3 A		0.039			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S	
Dynamic ^a							
Input Capacitance	C _{iss}			1800		pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, F = 1 MHz		180			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Qg			34	51		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_D = 3 A		8		nC	
Gate-Drain Charge ^c	Q _{gd}			12		1	
Gate Resistance	Rg		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25	ns	
Rise Time ^c	t _r	V_{DD} = 100 V, R _L = 5.2 Ω		50	75		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 3 \text{ A}, \text{ V}_{\text{GEN}}$ = 10 V, R_g = 2.5 Ω		30	45		
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Char	acteristics (1	Γ _C = 25 °C)					
Pulsed Current	I _{SM}				5	А	
Diode Forward Voltage ^b	V _{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dl/dt = 100 A/µs		180	250	ns	

Notes:

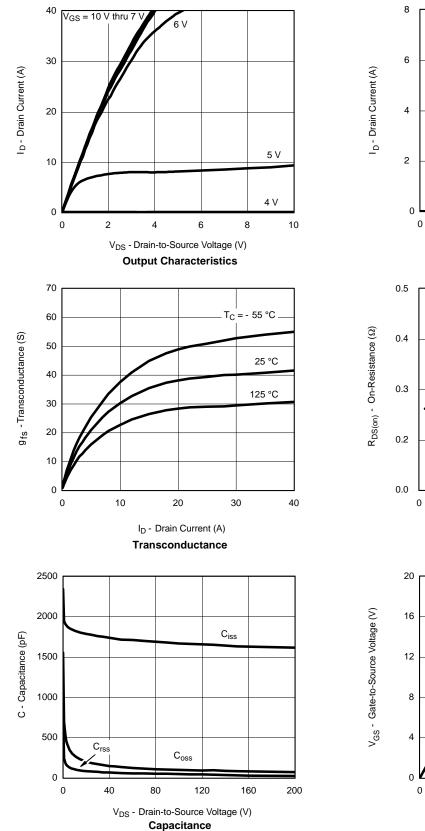
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

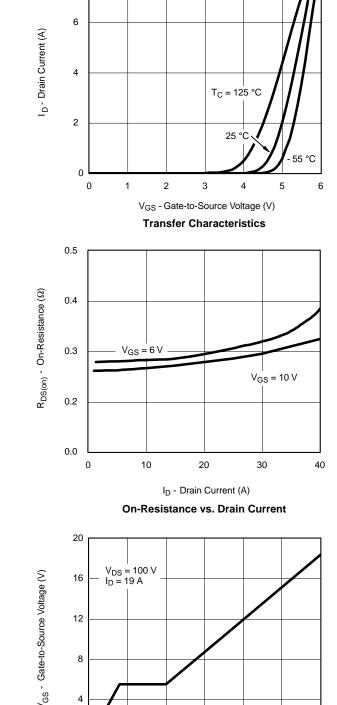
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



10

30

Q_g - Total Gate Charge (nC)

Gate Charge

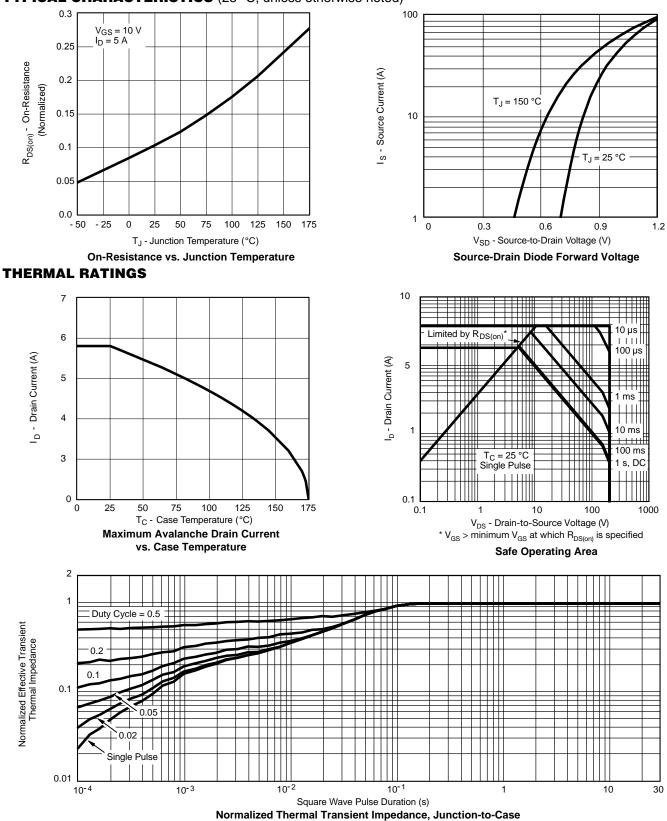
20

40

50

60

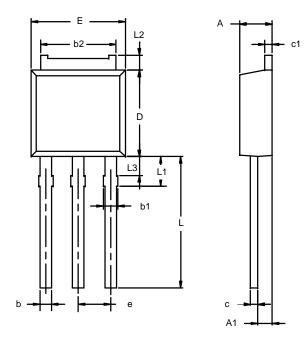




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



TO-251AA (DPAK)



	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

Note: Dimension L3 is for reference only.



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